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Intel Mobile Communications Ships World's Smallest HSPA+ Solution for 3G Smart Phones

Industry`s first HSPA+ solution offering true 21Mbps downlink performance based on a leading-edge 40nm baseband processor

NEUBIBERG, Germany & BARCELONA, Spain--(BUSINESS WIRE)-- Intel Mobile Communications, a leading vendor of advanced mobile semiconductors solutions for handheld devices, today announced shipment of its XMM(TM) 6260 platform to key customers. Optimized for smart phone architectures coupled with an application processor or as a standalone solution for PC modems and data cards, the advanced HSPA+ platform is based on the X-GOLD(TM) 626 baseband processor and the SMARTi(TM) UE2 RF transceiver. Combined with the 3GPP Release 7 protocol stack, the XMM 6260 platform comprises a fully integrated HSPA+ system solution supporting HSPA category 14 (21Mbps) in the downlink and category 7 (11.5Mbps) in the uplink.

"With shipping of the XMM 6260 platform ahead of schedule we continue the fast evolution of our leading baseband and transceiver technology by adding advanced HSPA+ features," said Prof. Dr. Hermann Eul, president of Intel Mobile Communications. "The fourth generation of successful 3G platforms underlines our technology leadership and our customers benefit from lower cost and space savings, which significantly increase design flexibility to create unique and feature-rich handsets and mobile Internet cards with innovative form factors."

The XMM 6260 platform is based on the X-GOLD 626 baseband processor, manufactured by TSMC in leading-edge 40nm process technology. The X-GOLD 626 integrates a power management unit, enabling world-class power consumption in both active and idle mode. The processor is combined with the SMARTi UE2 RF transceiver. Leveraging from a power-saving 65nm CMOS technology the transceiver uses a unique digital architecture that significantly reduces the number of power amplifiers and RF components, resulting in reduced board space and power consumption. The XMM 6260 smart phone modem platform enables HSPA+ designs in less than 600mm^2 PCB (Printed Circuit Board) area, making them among the smallest comparable solutions worldwide.

The common and scalable ARM11(TM)-based processor architecture used across all 2G and 3G platforms ensures Intel Mobile Communications customers a high degree of reuse of their hardware and software investment when developing handsets across the entire cellular portfolio. In addition, the platform includes numerous advanced 3GPP Release 7 features such as receive diversity, interference cancellation and CPC (Continuous Packet Connectivity) that significantly improve power consumption and system performance.

Availability

The XMM 6260 is available in volume and will be presented at the Intel Mobile Communications booth (Hall 1, Booth B22) during the Mobile World Congress in Barcelona from Feb. 14-17. Worldwide shipment to key customers has already started and design-in of the XMM 6260 is supported by a complete reference design.

About Intel Mobile Communications

Intel Mobile Communications develops and markets innovative semiconductor products and solutions for wireless communications leveraging its unique advantages in the areas of RF, Mixed Signal/power management, monolithic integration and comprehensive know-how in cellular software and systems. Intel Mobile Communications targets the fast growing market segments of smart phones, connected devices (e.g., tablets, USB dongles, mobile PCs, M2M), and ultra-low-cost/entry phones. Its roadmap is focused to provide the most cost-effective 2G/3G single-chip platforms for ULC phones up to entry-level smart phones and to offer best-in-class 3G/4G slim modem and RF solutions for mid-to high-end smart phones and connected devices. Intel Mobile Communication has formerly been a division of Infineon Technologies AG, called Wireless Solutions (WLS). Early in 2011, Intel completed the acquisition of Infineon's wireless business that has more than 3,500 employees worldwide.

Source: Intel